

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sandhu, et al.

Serial No.: 09/012,685

Filed: January 23, 1998

**For: LOW-RESISTANCE CONTACT TO
SILICON HAVING A TITANIUM
SILICIDE INTERFACE, AN
AMORPHOUS TITANIUM
NITRIDE BARRIER LAYER AND A
CONDUCTIVE PLUG**

Via Hand Delivery

Examiner: Nadaz

Group Art Unit: 1762

Attorney Docket No.: 3264.1US (92-280.04)

**POWER OF ATTORNEY, REVOCATION OF PRIOR
POWER OF ATTORNEY (37 C.F.R. § 1.36) and REQUEST TO
CHANGE CORRESPONDENCE ADDRESS (37 C.F.R. § 1.33(d))
with STATEMENT PURSUANT TO 37 C.F.R. § 3.73**

**Assistant Commissioner for Patents
Washington, D.C. 20231**

Sir:

As assignee of the entire interest in the above-identified application, all powers of attorney previously given herein are **HEREBY REVOKED** and the following attorneys are hereby appointed to prosecute and transact all business in the U.S. Patent and Trademark Office in connection herewith.

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In accordance with 37 C.F.R. § 1.33(d), please change the address for all purposes in connection with the above-identified patent and direct all communications to:

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Pursuant to 37 C.F.R. § 3.73, the undersigned representative of the Assignee has reviewed the evidentiary documents, specifically the Assignment to Micron Technology, Inc. recorded on February 6, 1997 at Reel 8389, Frame 0293, and certifies that to the best of his knowledge and belief, title remains in the name of Micron Technology, Inc. as Assignee of record of the entire interest in the above-identified patent application.

The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the Assignee, and to take the action set forth herein on behalf of the Assignee, pursuant to a resolution of its Board of Directors.

Respectfully submitted,

MICRON TECHNOLOGY, INC.

Dated: July 22, 1999

By: 
Michael L. Lynch, Esq.
Reg. No. 30,871
Chief Patent Counsel, an authorized
representative empowered to grant the
foregoing power of attorney

PATENT

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled LOW-RESISTANCE CONTACT TO SILICON HAVING A TITANIUM SILICIDE INTERFACE, AN AMORPHOUS TITANIUM NITRIDE BARRIER LAYER AND A REFRACTORY METAL PLUG, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, Section 1.56.

I hereby claim the benefit of any earlier filing date in the United States to which I am entitled under Title 35 of the United States Code, §120 and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35 of the United States Code, Section 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, Section 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

William R. Bachand
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, Section 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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